

AMENDMENTS TO THE ABSTRACT

Please substitute the following Abstract for any abstract now appearing in the currently filed specification:

A handling device is provided for wafers (semiconductor disks) or other disk-like substrates, for use with a storage device in which a plurality of wafers can be arranged with their surfaces aligned substantially parallel to one another, one behind another and outside a transport container. The handling device has a gripping device for removing individual wafers from the storage device and/or inserting individual wafers into the storage device, the gripping device having a plurality of grippers which are actuatable independently of one another to independently grip the wafers. The handling device has a movement device for moving the gripping device relative to the storage device. A first one of the grippers is capable of gripping a first one of the wafers while the gripping device is in a first position, and a second one of the grippers is capable of gripping a second one of the wafers while the gripping device is in a second position and the first gripper holds the first wafer.